# DATA SHEET

Part No.	AN41252A
Package Code No.	TQFP064-P-0707

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## AN41252A

## Optical disc motor drive IC

#### Overview

AN41252A is a single-chip IC that uses low-noise direct PWM (Pulse Width Modulation) drive in the spindle motor drive block and incorporates a PWM 9-channel driver necessary for optical pickup and mechanism driving.

It is effective in reducing noise, vibration and current dissipation of laptop computers.

#### ■ Features

- The spindle motor drive block adopts a single hall sensor, 3-phase full-wave and low-noise direct PWM drive technique.
- The actuator (focus, tracking, tilt) drive blocks use dead zone less, linear input and direct PWM drive technique.
- The stepping motor drive block uses sense resistor less, peak current sense feedback, linear input and direct PWM drive technique.
- Linear input and direct PWM drive technique for only beam expander drive block.
- Linear input and direct PWM drive technique for only loading drive block.
- Independent power supply pins are provided for each of the spindle, actuator, and stepping motor drive channels.

• Compact package: Less area 9.0 mm ☐ (Pins included)

Slim package 1.0 t [mm]

High power dissipation: On standard board (one side): 1.203 W (Glass-Epoxy:  $50 \times 50 \times 0.8$  t [mm])

• Functions: Spindle motor drive

Actuator (focus, tracking, tilt) drive

Stepping motor drive Beam expander drive Loading motor drive

• Drive voltages: 5 V

• Additional functions: Short brake / Reverse brake / Auto brake selection function

Spindle motor drive gain selection function

FG output frequency 1 time / 3 times selection function

Standby mode switch

Output reset function at V<sub>REF</sub> down

Thermal shutdown circuit

#### Applications

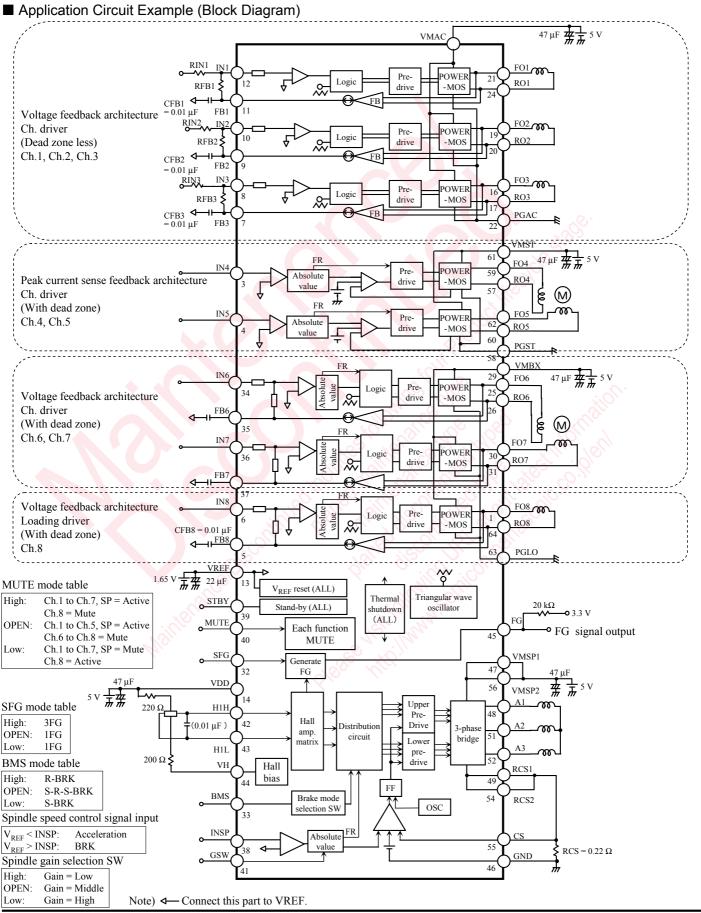
- Slim type
- Blu-Ray, HD-DVD, CD-R/RW, DVD-W
- DVD recording, various combination types
- 5 V system CD/DVD player

#### Package

• 64 pin plastic thin quad flat package (QFP Type)

### ■ Type

• Silicon monolithic bipolar IC



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## ■ Pin Descriptions

Pin No.	Pin name	Туре	Description
1	FO8	Output	Ch.8 non-inverted output
2	VMLO	Power supply	Ch.8 coil drive power supply
3	IN4	Input	Ch.4 control signal input
4	IN5	Input	Ch.5 control signal input
5	FB8	Output	Ch.8 feedback output
6	IN8	Input	Ch.8 control signal input
7	FB3	Output	Ch.3 feedback output
8	IN3	Input	Ch.3 control signal input
9	FB2	Output	Ch.2 feedback output
10	IN2	Input	Ch.2 control signal input
11	FB1	Output	Ch.1 feedback output
12	IN1	Input	Ch.1 control signal input
13	VREF	Input	Reference voltage input
14	VDD	Power supply	Control circuit power supply
15	VMAC1	Power supply	Ch.1, Ch.2, Ch.3 coil drive power supply 1
16	FO3	Output	Ch.3 non-inverted output
17	RO3	Output	Ch.3 inverted output
18	PGAC1	Ground	Ch.1, Ch.2, Ch.3 coil drive GND
19	FO2	Output	Ch.2 non-inverted output
20	RO2	Output	Ch.2 inverted output
21	FO1	Output	Ch.1 non-inverted output
22	PGAC2	Ground	Ch.1, Ch.2, Ch.3 coil drive GND
23	VMAC2	Power supply	Ch.1, Ch.2, Ch.3 coil drive power supply 2
24	RO1	Output	Ch.1 inverted output
25	FO6	Output	Ch.6 non-inverted output
26	RO6	Output	Ch.6 inverted output
27	N.C.		N.C.
28	PGBX	Ground	Ch.6, Ch.7 coil drive GND
29	VMBX	Power supply	Ch.6, Ch.7 coil drive power supply
30	FO7	Output	Ch.7 non-inverted output
31	RO7	Output	Ch.7 inverted output
32	SFG	Input	Spindle motor drive FG mode selection input
33	BMS	Input	Spindle motor drive brake mode selection input
34	IN6	Input	Ch.6 control signal input
35	FB6	Output	Ch.6 feedback output

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## ■ Pin Descriptions (continued)

Pin No.	Pin name	Туре	Description			
36	IN7	Input	Ch.7 control signal input			
37	FB7	Output	Ch.7 feedback output			
38	INSP	Input	pindle motor drive control signal input			
39	STBY	Input	otal shutdown input			
40	MUTE	Input	Mute control pin			
41	GSW	Input	Spindle motor drive gain selection input			
42	н1н	Input	Spindle motor drive hall element positive input			
43	H1L	Input	Spindle motor drive hall element negative input			
44	VH	Output	Spindle motor drive hall bias output			
45	FG	Output	Spindle motor drive FG signal output (O.D. output)			
46	GND	Ground	Control circuit GND			
47	VMSP1	Power supply	Spindle motor drive power supply 1			
48	A1	Output	Spindle motor drive output 1			
49	RCS1	Output	Spindle motor drive common source output 1			
50	N.C.	_	N.C.			
51	A2	Output	Spindle motor drive output 2			
52	A3	Output	Spindle motor drive output 3			
53	N.C.	-	N.C.			
54	RCS2	Output	Spindle motor drive common source output 2			
55	CS	Input	Spindle motor drive output current detection			
56	VMSP2	Power supply	Spindle motor drive power supply 2			
57	RO4	Output	Ch.4 inverted output			
58	PGST	Ground	Ch.4, Ch.5 motor drive GND			
59	FO4	Output	Ch.4 non-inverted output			
60	RO5	Output	Ch.5 inverted output			
61	VMST	Power supply	Ch.4, Ch.5 motor drive power supply			
62	FO5	Output	Ch.5 non-inverted output			
63	PGLO	Ground	Ch.8 motor drive GND			
64	RO8	Output	Ch.8 inverted output			

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## ■ Absolute Maximum Ratings

A No.	Parameter	Symbol	Rating	Unit	Note
1	Supply voltage	$\begin{matrix} V_{\text{MSP}}, V_{\text{MST}}, \\ V_{\text{MAC}}, V_{\text{MBX}}, \\ V_{\text{MLO}}, V_{\text{DD}} \end{matrix}$	6.5	V	*1
		$I_{VMSP}$	1 200	mA	*2
		I <sub>VMST</sub>	2 000	mA	*2
	Supply current	I <sub>VMAC</sub>	3 000	mA	*2
2		$I_{VMBX}$	1 000	mA	*2
		I <sub>VMLO</sub>	1 100	mA	*2
		$I_{VDD}$	100	mA	*2
3	Power dissipation	P <sub>D</sub>	290.2	mW	*3
4	Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C	*4
5	Storage temperature	$T_{stg}$	-55 to +150	°C	*4

- Note) \*1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.
  - \*2: Make sure that each of Ch.1 to Ch.5 does not have a current flow exceeding 1 000 mA. Make sure that each of Ch.6 to Ch.7 does not have a current flow exceeding 500 mA. Make sure that Ch.8 does not have a current flow exceeding 1 100 mA.
  - \*3: The power dissipation shown is the value at  $T_a = 85^{\circ}$ C for the independent (unmounted) IC package without a heat sink. When using this IC, refer to the  $\bullet$   $P_D T_a$  diagram in the  $\blacksquare$  Technical Data and use under the condition not exceeding the allowable value.
  - \*4: Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for T<sub>a</sub> = 25°C.

## ■ Operating Supply Voltage Range

Parameter	Symbol	Range	Unit	Note
in iso	$V_{\mathrm{DD}}$	4.0 to 5.5		
Supply voltage range	$\begin{vmatrix} V_{\text{MAC}}, V_{\text{MST}}, \\ V_{\text{MSP}}, V_{\text{MBX}}, \\ V_{\text{MLO}} \end{vmatrix}$	$3.5$ to $V_{DD}$	V	*

Note) \*: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

■ Electrical Characteristics at  $V_{DD} = V_{MSP} = V_{MAC} = V_{MST} = V_{MBX} = V_{MLO} = 5 \text{ V}, V_{REF} = 1.65 \text{ V}, STBY = 3.3 \text{ V}$ Note)  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$  unless otherwise specified.

В	<b>D</b> 1	0 1 1	0 86		Limits		11	Nata			
No.	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Note			
Con	Common block										
Sup	ply current										
1	Power supply current in standby mode	$I_{VMS}$	STBY = Low	_	_	20	μΑ	_			
2	Supply current in standby mode	$I_{DDS}$	STBY = Low	_		20	μΑ				
3	Supply current under no input	$I_{DDA}$	STBY = High	_	12	16	mA				
Star	ndby operation				300	٠,					
4	High-level STBY input voltage	$V_{SBH}$	(Active)	1.8	2	$V_{DD}$	V				
5	Low-level STBY input voltage	$V_{\mathrm{SBL}}$	(Standby)	- N	_	0.7	V				
Mut	e operation										
6	High-level MUTE input voltage	V <sub>MUTEH</sub>	4 4 Mic	2.2	_	$V_{\mathrm{DD}}$	V	_			
7	Low-level MUTE input voltage	V <sub>MUTEL</sub>	- S40	0		0.5	V				
8	MUTE input current range for open operation	I <sub>MUTE</sub>	-4011	-5	_	5	μΑ	_			
VRE	EF reset		Will So the	>		Silo.					
9	High-level VREF reset input voltage	V <sub>RRH</sub>	(Reset)	2.8	ROY	$V_{\mathrm{DD}}$	V	_			
10	Active VREF reset input voltage	V <sub>RRM</sub>	(Active)	1.15	7 <u>10,</u> 10	2.15	V				
11	Low-level VREF reset input voltage	V <sub>RRL</sub>	(Reset)	10/0	<i>`</i> &;	0.5	V				
Spir	ndle driver	. 16	o leo ille collinso		ilo.						
Spir	ndle motor drive hall bias	dille	by the gradient sp	1000							
12	Hall bias resistance	$R_{HB}$	$I_{HB} = 20 \text{ mA}$	20	30	40	Ω	_			
Spir	ndle motor drive hall signal comparato	or	by a fill of the								
13	Input bias current	$I_{BH}$	10 Sell	-3		3	μΑ				
14	Common-mode input voltage range	$V_{\mathrm{BHR}}$	isit — unn	1.5	(2.5)	4.0	V	_			
15	Minimum input amplitude	$V_{\rm INH}$	8 1.0.	80	_	_	mV[p-p]	_			
Spir	ndle motor drive torque control		0/892 Hills								
16	Input bias current	$I_{INSP}$	_	- 1	_	1	mA	_			
17	Input dead zone (one side)	$INSP_{DZ}$	_	7	40	88	mV				
18	Input/output gain (High torque mode)	A <sub>CS(High)</sub>	GSW = 0 V, $R_{CS} = 0.22 \Omega$	1.13	1.5	1.87	A/V				
19	Input/output gain (Middle torque mode)	A <sub>CS(Mid)</sub>	GSW = OPEN, $R_{CS} = 0.22 \Omega$	0.565	0.75	0.935	A/V				
20	Input/output gain (Low torque mode)	A <sub>CS(Low)</sub>	GSW = 3.3 V, $R_{CS} = 0.22 \Omega$	0.24	0.34	0.44	A/V	_			
21	Torque limit current (High torque mode)	$I_{TLH}$	GSW = 0 V, $R_{CS} = 0.22 \Omega$ ,	800	1 000	1 200	mA				
22	Torque limit current (Middle torque mode)	$I_{TLM}$	GSW = OPEN, $R_{CS} = 0.22 \Omega$	440	550	660	mA				

■ Electrical Characteristics at V<sub>DD</sub> = V<sub>MSP</sub> = V<sub>MSP</sub> = V<sub>MST</sub> = V<sub>MST</sub> = V<sub>MEX</sub> = V<sub>MLO</sub> = 5 V, V<sub>REF</sub> = 1.65 V, STBY = 3.3 V (continued)

Note)  $T_a = 25^{\circ}C \pm 2^{\circ}C$  unless otherwise specified.

В	Davamatas	Symbol		Limits			1.124	Noto
No.	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Note
Spino	lle motor drive output							
23	Upper-side output ON resistance	$R_{OH}$	$I_{O} = -1~000 \text{ mA}$	0.13	0.25	0.37	Ω	] —
24	Lower-side output ON resistance	$R_{OL}$	$I_0 = +1~000~\text{mA}$	0.13	0.25	0.37	Ω	_
Spino	lle motor drive PWM frequency							
25	PWM frequency max. (High torque mode)	$PWM_H$	INSP = 3.3 V, V <sub>REF</sub> = 1.65 V, GSW = 0 V	105	150	195	kHz	_
26	PWM frequency min. (High torque mode)	$PWM_L$	$\frac{\text{INSP} = \text{V}_{\text{REF}} + \text{INSPDZ} + 10 \text{ mV}, \text{V}_{\text{REF}} = 1.65 \text{ V}, \text{GSW} = 0 \text{ V}}{1.65 \text{ V}}$	10	20	30	kHz	
27	PWM frequency (Middle torque mode)	PWM <sub>M</sub>	INSP = 3.3 V, V <sub>REF</sub> = 1.65 V, GSW = OPEN	90	125	160	kHz	
28	PWM frequency (Low torque mode)	$PWM_S$	INSP = 3.3 V, V <sub>REF</sub> = 1.65V, GSW = 3.3 V	14	20	26	kHz	
Spino	lle motor drive gain selection		39LL (27).;			:00:		
29	High-level GSW input voltage	$V_{GSWH}$	(Low torque mode)	2.2	_	$V_{DD}$	V	-
30	Low-level GSW input voltage	$V_{GSWL}$	(High torque mode)	0	10%	0.5	V	_
31	GSW input current range for open operation	$I_{GSW}$	(Middle torque mode)	Z -5		5	μΑ	_
Spino	lle motor drive FG		Peg 160 Miles Out 180	Jil .	ilo.			
32	High-level SFG input voltage	$V_{SFGH}$	in his line to	2.2	_	V <sub>DD</sub>	V	-
33	Low-level SFG input voltage	$V_{SFGL}$	ange is co. The	0		0.5	V	
34	SFG input current range for open operation	$I_{SFG}$	Pro _ initial light	-5	_	5	μΑ	
35	High-level FG output voltage	$FG_H$	$V_{FG} = 3.3 \text{ V}, I_{FG} = -0.01 \text{ mA}, RFG = 20 \text{ k}\Omega$	2.6	_	_	V	_
36	Low-level FG output voltage	$FG_L$	$V_{FG} = 3.3 \text{ V}, I_{FG} = +0.01 \text{ mA}, RFG = 20 \text{ k}\Omega$	_	_	0.2	V	
Spino	lle motor drive brake mode sele	ction	0/6yz //1/14					
37	High-level BMS input voltage	$V_{\mathrm{BMSH}}$	(Reverse brake)	2.2	_	$V_{DD}$	V	
38	Low-level BMS input voltage	$V_{\mathrm{BMSL}}$	(Short brake)	0		0.5	V	
39	BMS input current range for open operation	$I_{BMS}$	_	-5		5	μΑ	_

■ Electrical Characteristics at V<sub>DD</sub> = V<sub>MSP</sub> = V<sub>MSP</sub> = V<sub>MST</sub> = V<sub>MST</sub> = V<sub>MEX</sub> = V<sub>MLO</sub> = 5 V, V<sub>REF</sub> = 1.65 V, STBY = 3.3 V (continued)

Note)  $T_a = 25^{\circ}C \pm 2^{\circ}C$  unless otherwise specified.

В	Developed	0	O a markiti a mar		Limits		1.1	NI-4-
No.	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Note
Chan	nel driver							
Actua	ator drive block (Ch.1 to Ch.3)							
40	Ch.1, Ch.2, Ch.3 output ON resistance (upper + lower)	R <sub>ON1</sub> R <sub>ON2</sub> R <sub>ON3</sub>	$I_{O} = \pm 500 \text{ mA}$	0.4	0.9	1.2	Ω	
41	Ch.1,Ch.2, Ch.3 input/output gain (+)	G1,G2, G3	$R_{L1-3} = 8 \Omega,$ RIN1, 2, 3 = 15 k $\Omega$	15.5	17.5	19.5	dB	
42	(+)/(–) relative gain	GR	Ch.1 to Ch.3 $R_{L1-3} = 8 \Omega$	-1.5	S —	+1.5	dB	
43	Output offset voltage	V <sub>OFS</sub>	$R_{L.1-3} = 8 \Omega$ $V_{IN} = V_{REF} = 1.65 V$	-50	_	+50	mV	
44	PWM frequency	FTR	1 - 1	150	200	250	kHz	_
Stepp	ping motor drive block (Ch.4, Cl	h.5)	, Pro			•		
45	Output ON resistance (upper + lower)	R <sub>ON4</sub> R <sub>ON5</sub>	$R_{L4-5} = 12 \Omega,$ $I_O = \pm 500 \text{ mA}$	0.4	1.0	1.3	Ω	_
46	Input/output gain (+)	G4, G5	$R_{L4-5} = 12 \Omega$	0.45	0.6	0.75	A/V	_
47	(+)/(-) relative gain	GR	Ch.4 to Ch.5 $R_{L4-5} = 12 \Omega$	-15	. **	15	%	_
48	Relative gain between Ch.4 and Ch.5	GR45	$(G4/G5-1) \times 100\%$	-15	o <u> </u>	15	%	
49	Input dead zone (one side)	IN45 <sub>DZ</sub>	180 11/4 10/11/80 1	5	20	40	mV	
50	Torque limit current	I <sub>TL45</sub>	De Green Line Files Files Since See	400	500	600	mA	_
51	PWM frequency	FTR	100 18 1	73	104	135	kHz	
52	Input bias current	$I_{\mathrm{B45}}$	610 -01 100 100 100 100 100 100 100 100 1	-5	_	5	μΑ	_
Bean	n expander drive block (Ch.6, 0	Ch.7)	Mon certification					
53	Output ON resistance (upper + lower)	R <sub>ON6</sub>	$R_{L6-7} = 30 \Omega,$ $I_O = \pm 500 \text{ mA}$	0.7	1.5	1.9	Ω	_
54	Input/output gain (+)	G6	$R_{L6-7} = 30 \Omega$	15	17	19	dB	_
55	(+)/(-) relative gain	GR	Ch.6 to Ch.7 $R_{L6-7} = 30 \Omega$	-1.5		+1.5	dB	_
56	Output offset voltage	V <sub>OFS</sub>	$R_{L.6-7} = 30 \Omega$ $V_{IN} = V_{REF} = 1.65 V$	-50	_	+50	mV	
57	Input dead zone	VDZ3	$R_{L6-7} = 30 \ \Omega$	10	25	40	mV	_
58	PWM frequency	FTR	_	150	200	250	kHz	_

■ Electrical Characteristics at  $V_{DD} = V_{MSP} = V_{MAC} = V_{MST} = V_{MBX} = V_{MLO} = 5 \text{ V}, \ V_{REF} = 1.65 \text{ V}, \ STBY = 3.3 \text{ V}$ 

Note)  $T_a = 25^{\circ}C \pm 2^{\circ}C$  unless otherwise specified.

В	B Doromotor		O and this ma		Limits		Unit	NI-4-
No.	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Note
Chan	nel driver (continued)							
Loadi	ing motor drive block (Ch.8)							
59	Output ON resistance (upper + lower)	R <sub>ON6</sub>	$R_{L8} = 12 \Omega$ , $I_O = \pm 500 \text{ mA}$	0.4	0.9	1.2	Ω	
60	Input/output gain (+)	G6	$R_{L8} = 12 \Omega$	15	17	19	dB	
61	(+)/(–) relative gain	GR	Ch.8 $R_{L8} = 12 \Omega$	-1.5	100 S	+1.5	dB	
62	Output offset voltage	V <sub>OFS</sub>	$R_{L8} = 12 \Omega$ $V_{IN} = V_{REF} = 1.65 V$	-50	S _	+50	mV	
63	Input dead zone	VDZ3	$R_{L8} = 12 \Omega$	10	25	40	mV	
64	PWM frequency	FTR	No.	150	200	250	kHz	

■ Electrical Characteristics (Reference values for design) at V<sub>DD</sub> = V<sub>MSP</sub> = V<sub>MAC</sub> = V<sub>MST</sub> = V<sub>MBX</sub> = V<sub>MLO</sub> = 5 V, V<sub>REF</sub> = 1.65 V, STBY = 3.3 V

Note) T<sub>a</sub> = 25°C±2°C unless otherwise specified.

The characteristics listed below are reference values derived from the design of the IC and are not guaranteed by inspection. If a problem does occur related to these characteristics, we will respond in good faith to user concerns.

В	Devementer	Cymphal	Reference v	Reference val		alues	Linit N	
No.	Parameter	Parameter Symbol Conditions		Min	Тур	Max	Unit	Note
			Me allin all rice in the a	200,000				
65	Thermal shutdown circuit operating temperature	$T_{TSD}$		627.0	160	_	°C	
66	Thermal shutdown hysteresis width	$\Delta T_{TSD}$	6. — Miles High		30	_	°C	

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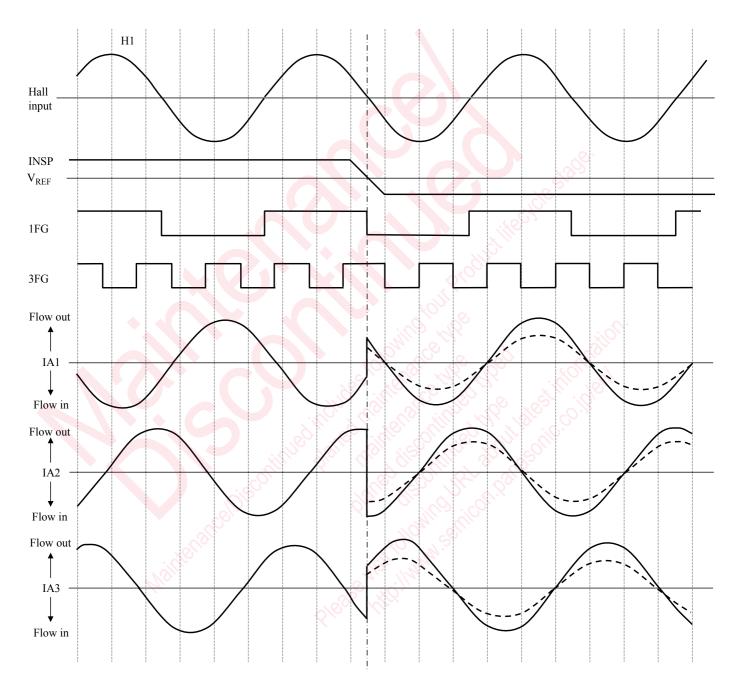
## ■ Control Pin Mode Table

Note) See parameters B No. 6 to 8, B No. 29 to 34 and B No. 37 to 39 in the ■ Electrical Characteristics for control voltage retention ranges.

Pin	Description		Pin voltage		Remarks
No.	Description	Low	Open	High	Remarks
41	Spindle gain selection SW	High torque mode	Middle torque mode	Low torque mode	Torque mode control
33	Spindle brake mode selection SW	Short Brake	S-R-S-Brake	Reverse Brake	Brake mode control
32	Spindle FG mode selection SW	1FG	1FG	3FG	FG control
		Ch.1-3 mute	Ch.1-3 active	Ch.1-3 active	
		Ch.4-5 mute	Ch.4-5 active	Ch.4-5 active	×900.
40	Mute control pin	Ch.6-7 mute	Ch.6-7 mute	Ch.6-7 active	Ch.1-8, SP control
		Ch.8 active	Ch.8 mute	Ch.8 mute	
		SP mute	SP active	SP active	

## ■ Technical Data

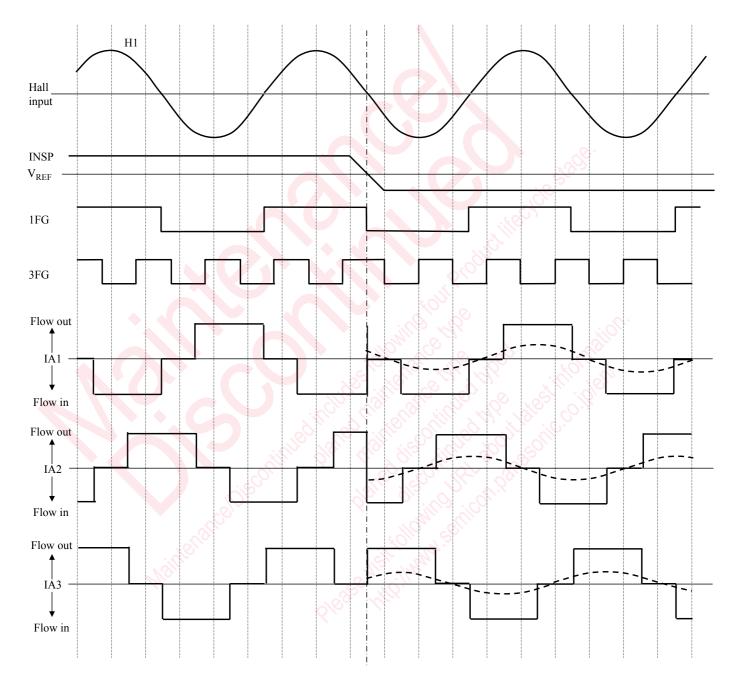
• Phase condition between hall input and output current (High torque mode, Middle torque mode)



BMS = High : Reverse brake BMS = Low : Short brake

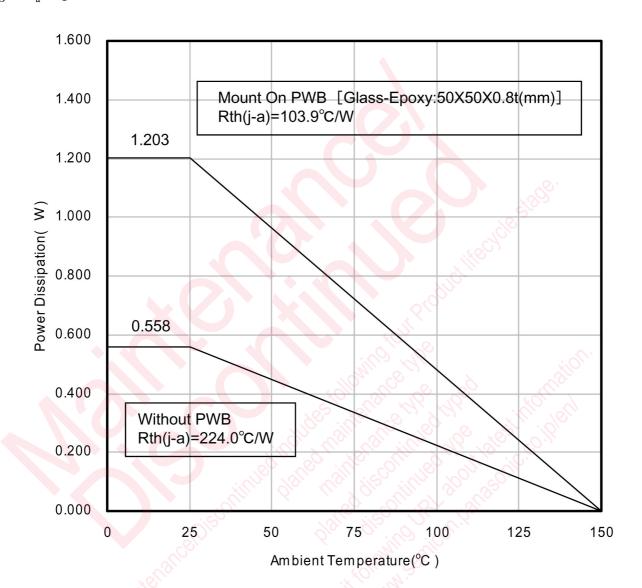
## ■ Technical Data (continued)

• Phase condition between hall input and output current (Low torque mode)



BMS = High : Reverse brakeBMS = Low : Short brake

## ■ Technical Data (continued)



## ■ Usage Notes

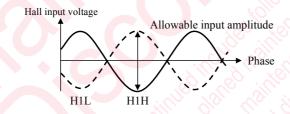
1. Standby operation, thermal shutdown (TSD), V<sub>REF</sub> reset operation

STBY	TSD	$V_{REF}$	MUTE	Ch.1 to Ch.3	Ch.4, Ch.5	Ch.6, Ch.7	Ch.8	SP
≥ 1.8 V	≤ 160°C	1.15 V to 2.15 V	≥ 2.2 V	Active	Active	Active	п. 7	Active
			OPEN			11: 7	Hi-Z	
			≤ 0.5 V	Hi-Z	Hi-Z	Hi-Z	Active	Hi-Z
		≤ 0.5 V ≥ 2.8 V		Hi-Z				
	≥ 160°C	_						
≤ 0.7 V	_			Hi-Z, The current into the circuit is intercepted.				

- 2. Make sure to power ON/OFF at standby mode ( $V_{STBY}$ : Low).
- 3. This IC is designed assuming the range of  $V_{REF}$  is 1.15 V to 2.15 V under the conditions where the ambient temperature is  $25^{\circ}\text{C}\pm2^{\circ}\text{C}$  and  $V_{DD}$  is 5 V $\pm10\%$ .

Before using the IC, ensure that fluctuation of the ambient temperature or the power supply voltage does not occur any problems.

4. The hall amp, allowable input amplitude indicates that shown in the figure below. Hall amplitude should be 80 mV[p-p] or more including the variation of hall elements and temperature characteristics under the temperature conditions you use. Hall input with 200 mV[p-p] or more is recommended in order to raise detection accuracy of hall position.



- 5. The PWM frequency of spindle motor drive is variable in the range between 20 kHz and 150 kHz continuously according to the torque control.
- 6. When using FG with ×3 frequency, keep SFG pin (Pin 32) open (Hi-Z).
- 7. When using brake at auto switching mode, keep BMS pin (Pin 33) open (Hi-Z).
- 8. Check the characteristics carefully before using this IC.

  Preserve sufficient margin in consideration of dispersion of external components and our ICs including not only static characteristics but transition characteristics when using this IC changing external circuit constants.
- 9. Apply voltage from a low-impedance source to  $V_{REF}$ ,  $V_{DD}$  and connect a bypass capacitor to each as near the IC as possible.
- 10. It is not recommended to use solder dipping.
- 11. Each voltage to  $V_{MSP}$ ,  $V_{MAC}$ ,  $V_{MST}$ ,  $V_{MBX}$ ,  $V_{MLO}$  should not exceed the voltage applied to  $V_{DD}$ .
- 12. 180°C commutation mode for high (GSW = Low) and middle (GSW = OPEN) torque mode. 120°C commutation mode for low torque mode (GSW = High).

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#### ■ Usage Notes (continued)

- 13. Notes of Power LSI
  - 1) Please carry out the thermal design with sufficient margin such that the power dissipation will not be exceeded, based on the conditions of power supply, load and ambient temperature.
- 2) Protection circuit has been built-in to ensure the safety in the event of abnormal operation. Therefore, please design such that the protection circuit does not work during normal operation. Especially in the over-temperature protection circuit, if the area of safe operation or the absolute maximum rating is momentarily exceeded, as in the event of output pin to V<sub>DD</sub> short (Power supply fault), or output pin to GND short (Ground fault), then the LSI might be damaged before the over-temperature protection circuit could operate.
- 3) Pay attention in the pattern layout in order to prevent damage due to short circuit between pins. In addition, for the pin configuration, please refer to the Pin Descriptions.
- 4) Unless specified in the product specifications, please make sure that negative voltage or excessive voltage are not applied to the pins because the device might be damaged, which could happen due to negative voltage or excessive voltage generated during the ON and OFF timing when the inductive load of a motor coil or actuator coils of optical pick-up is being driven.
- 5) Be sure not to mount the LSI in the reverse direction onto the PCB. It might be damaged when the electricity is turned on.
- 6) Perform a visual inspection on the printed-circuit-board before turning on the power supply, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
- 7) Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-V<sub>DD</sub> short, output pin-GND short, or output-to-output-pin short (load short). And, safety measures such as an installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.
- 8) When using the LSI for model development or new products, perform fully the safety verification including the long-term reliability for each product.
- 9) Verify the risk due to the breakdown of external parts.

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